

In the claims:

1. (Cancelled)
2. (Cancelled)
3. (Original) A method of production of a semiconductor package mounting a capacitor for suppressing fluctuation of a power supply voltage, comprising:
 - providing an attachment hole passing through a board in a thickness direction and
 - press-fitting into said attachment hole a capacitor cable comprised of a conductor wire at the core, a high dielectric constant material coaxially covering the conductor wire at a predetermined thickness, and a conductor sheath covering the out circumference of the high dielectric constant material so as to attach the capacitor to said board.
4. (Original) A method of production of a semiconductor package mounting a capacitor for suppressing fluctuation of a power supply voltage, comprising:
 - providing an attachment hole passing through a board in a thickness direction,
 - forming a conductor layer at an inner wall of said attachment hole, and,
 - press-fitting into said attachment hole formed with said conductor layer a capacitor cable comprised of a conductor wire at the core and a high dielectric constant material coaxially covering the conductor wire at a predetermined thickness so as to attach the capacitor to said board.